

P/1071-1524

METHOD OF MANUFACTURING NONRECIPROCAL  
CIRCUIT DEVICE, NONRECIPROCAL CIRCUIT DEVICE,  
AND COMMUNICATION APPARATUS

ABSTRACT OF THE DISCLOSURE

5           A compact and highly reliable nonreciprocal circuit  
device can be manufactured at low cost. Marking is  
clearly performed on a surface of the nonreciprocal  
circuit device. In a method of manufacturing the  
nonreciprocal circuit device, after components  
10           constituting the device are joined together, solder is  
applied at portions where the components are bonded with  
each other. The magnetic force of a permanent magnet is  
adjusted and then laser marking is performed on a surface  
of a metal case. Next, the nonreciprocal circuit device  
15           is heated to perform together solder bonding, thermal  
aging of the permanent magnet, and the removal of stains  
left due to marking. Then, after checking the  
characteristics of the device, delivery inspection is  
conducted to complete the manufacturing process.